

# Global Flip Chip Market, 2021-2027

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## Abstracts

The global flip chip market is projected to grow at a compound annual growth rate (CAGR) of 6.3% during the forecast period 2021-2027, according to the new report published by Gen Consulting Company.

The report provides in-depth analysis and insights regarding the current global market scenario, latest trends and drivers into global flip chip market. It offers an exclusive insight into various details such as market size, key trends, competitive landscape, company share of market leaders, growth rate and market segments.

The flip chip market is segmented on the basis of packaging technology, bumping technology, end user, and region. The flip chip market is segmented as below:

By Packaging Technology:

2.5D IC

2D IC

3D IC

By Bumping Technology:

copper pillar

gold bumping

solder bumping

others

#### By End User:

aerospace & defense

automotive & transport

electronics

healthcare

industrial

IT

others

#### By Region:

region

Asia-Pacific

Europe

North America

Middle East and Africa (MEA)

South America

The flip chip industry is characterized by a high level of market share concentration. The market research report covers the analysis of key stake holders of the flip chip market. Some of the leading players profiled in the report include Advanced Micro Devices, Inc.,

Amkor Technology, Inc., Apple Inc., Fujitsu Limited, IBM Corporation, Intel Corporation, Samsung Electronics Co., Ltd., Taiwan Semiconductor Manufacturing Company Limited, Texas Instruments Incorporated, among others.

\*list is not exhaustive, request free sample to get a complete list of companies

### Historical & Forecast Period

This research report provides analysis for each segment from 2017 to 2027 considering 2020 to be the base year.

### Scope of the Report

To analyze and forecast the market size of the global flip chip market.

To classify and forecast the global flip chip market based on packaging technology, bumping technology, end user, and region.

To identify drivers and challenges for the global flip chip market.

To examine competitive developments such as mergers & acquisitions, agreements, collaborations and partnerships, etc., in the global flip chip market.

To conduct pricing analysis for the global flip chip market.

To identify and analyze the profile of leading players operating in the global flip chip market.

### Why Choose This Report

Gain a reliable outlook of the global flip chip market forecasts from 2021 to 2027 across scenarios.

Identify growth segments for investment.

Stay ahead of competitors through company profiles and market data.

The market estimate for ease of analysis across scenarios in Excel format.

Strategy consulting and research support for three months.

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## Contents

### **PART 1. INTRODUCTION**

- 1.1 Market Definition
- 1.2 Key Benefit
- 1.3 Market Segment

### **PART 2. METHODOLOGY**

- 2.1 Primary
- 2.2 Secondary

### **PART 3. EXECUTIVE SUMMARY**

### **PART 4. MARKET OVERVIEW**

- 4.1 Introduction
- 4.2 Market Size and Forecast
- 4.3 Market Dynamics
  - 4.3.1 Drivers
  - 4.3.2 Restraints
- 4.4 Impact of COVID-19 Pandemic

### **PART 5. GLOBAL MARKET FOR FLIP CHIP BY PACKAGING TECHNOLOGY**

- 5.1 2.5D Ic
  - 5.1.1 Market Size and Forecast
- 5.2 2D Ic
  - 5.2.1 Market Size and Forecast
- 5.3 3D Ic
  - 5.3.1 Market Size and Forecast

### **PART 6. GLOBAL MARKET FOR FLIP CHIP BY BUMPING TECHNOLOGY**

- 6.1 Copper Pillar
  - 6.1.1 Market Size and Forecast
- 6.2 Gold Bumping
  - 6.2.1 Market Size and Forecast

## 6.3 Solder Bumping

### 6.3.1 Market Size and Forecast

## 6.4 Others

### 6.4.1 Market Size and Forecast

## **PART 7. GLOBAL MARKET FOR FLIP CHIP BY END USER**

### 7.1 Aerospace & Defense

#### 7.1.1 Market Size and Forecast

### 7.2 Automotive & Transport

#### 7.2.1 Market Size and Forecast

### 7.3 Electronics

#### 7.3.1 Market Size and Forecast

### 7.4 Healthcare

#### 7.4.1 Market Size and Forecast

### 7.5 Industrial

#### 7.5.1 Market Size and Forecast

### 7.6 It

#### 7.6.1 Market Size and Forecast

### 7.7 Others

#### 7.7.1 Market Size and Forecast

## **PART 8. GLOBAL MARKET FOR FLIP CHIP BY REGION**

### 8.1 Asia-Pacific

#### 8.1.1 Market Size and Forecast

### 8.2 Europe

#### 8.2.1 Market Size and Forecast

### 8.3 North America

#### 8.3.1 Market Size and Forecast

### 8.4 Middle East And Africa (Mea)

#### 8.4.1 Market Size and Forecast

### 8.5 South America

#### 8.5.1 Market Size and Forecast

## **PART 9. KEY COMPETITOR PROFILES**

### 9.1 Advanced Micro Devices, Inc.

### 9.2 Amkor Technology, Inc.

9.3 Apple Inc.

9.4 Fujitsu Limited

9.5 IBM Corporation

9.6 Intel Corporation

9.7 Samsung Electronics Co., Ltd.

9.8 Taiwan Semiconductor Manufacturing Company Limited

9.9 Texas Instruments Incorporated

\*LIST IS NOT EXHAUSTIVE

## **PART 10. PATENT ANALYSIS**

10.1 Patent Statistics

10.2 Regional Analysis

10.3 Trends Analysis

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